

What is claimed is:

1. An electroless plating method comprising:
facing a surface, to be plated, of a substrate downwardly;

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processing said surface to be plated by bringing said surface to be plated into contact with an electroless plating treatment liquid.

10 2. An electroless plating method according to claim 1, wherein gas generated on said surface to be plated is removed from said surface to be plated by bringing said surface to be plated into contact with said electroless plating treatment liquid in such a state that said surface to be plated is inclined.

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3. An electroless plating method according to claim 1, wherein gas generated on said surface to be plated is removed from said surface to be plated by forming a flow of said electroless plating treatment liquid in a certain direction on said surface to be plated and entraining said gas generated on said surface to be plated with said flow of said electroless plating treatment liquid.

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